

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
60V	17mΩ@10V	45A

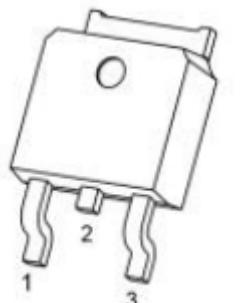
Feature

- Fast Switching
- Low Gate Charge and Rdson
- 100% Single Pulse avalanche energy Test

Applications

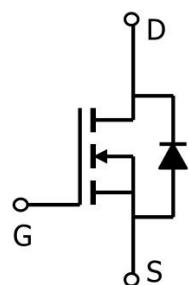
- DC-DC Converter
- Ideal for high-frequency switching and synchronous rectification

Package

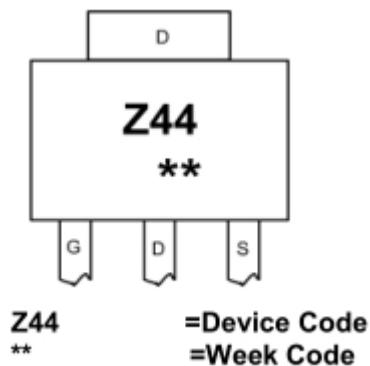


TO-252(G:1 D:2 S:3)

Circuit diagram



Marking



Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 25	V
Continuous Drain Current ¹ ($T_c=25^\circ\text{C}$)	I_D	45	A
Pulsed Drain Current ²	I_{DM}	108	A
Single Pulse Avalanche Energy ³	E_{AS}	65	mJ
Total Power Dissipation($T_c=25^\circ\text{C}$)	P_D	90	W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	1.38	$^\circ\text{C}/\text{W}$
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ\text{C}$

Electrical characteristics

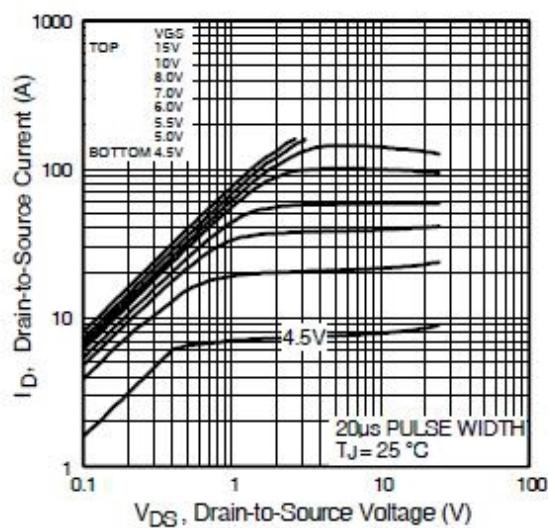
($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	$\text{BV}_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	60			V
Bvdss Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$I_D = 1\text{mA}$, Reference 25°C		0.058		$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 48\text{V}, V_{GS} = 0\text{V}$		25		μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 25\text{V}, V_{DS} = 0\text{V}$			± 100	μA
Gate threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	4	V
Static Drain-Source on-Resistance	$R_{DS(\text{on})}$	$V_{GS} = 10\text{V}, I_D = 25\text{A}$		17	22	$\text{m}\Omega$
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		1476		pF
Output capacitance	C_{oss}			354		
Reverse transfer capacitance	C_{rss}			90		
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = 44\text{V}, V_{GS} = 10\text{V}, I_D = 25\text{A}$		36		nC
Gate-Source Charge	Q_{gs}			5		
Gate-Drain Charge	Q_{gd}			9		
Turn-on Delay Time	$T_{d(\text{on})}$	$V_{DD} = 28\text{V}, V_{GS} = 10\text{V}, R_G = 12\Omega, I_D = 25\text{A}$		12		nS
Turn-on Rise Time	T_r			60		
Turn-Off Delay Time	$T_{d(\text{off})}$			44		
Turn-Off Fall Time	t_f			45		

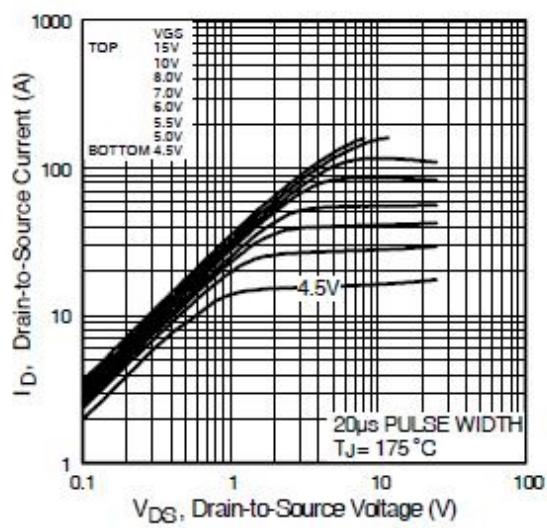
Notes:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $R_G = 25\Omega, L = 34\text{mH}$

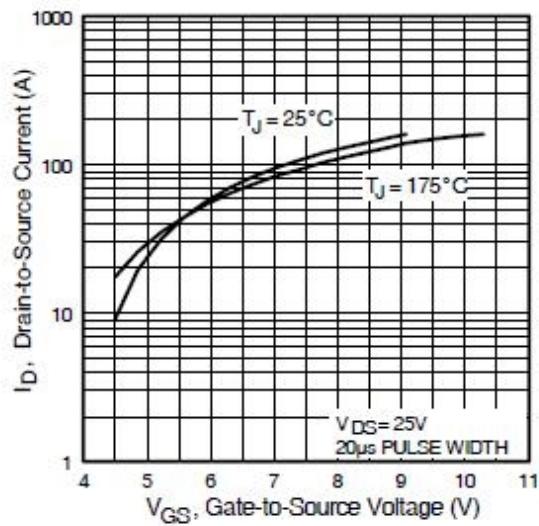
Typical Characteristics



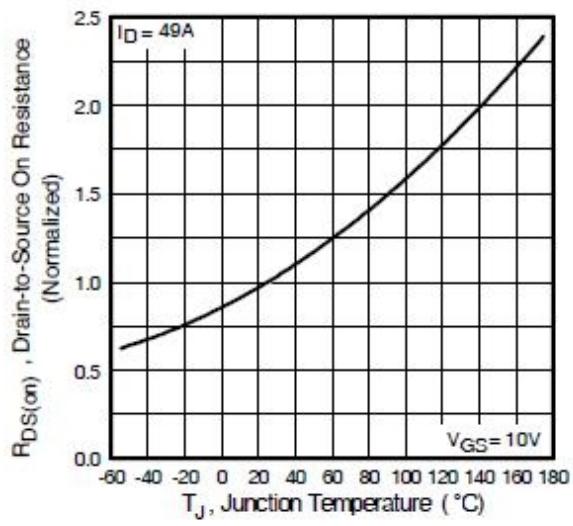
Typical Output Characteristics



Typical Output Characteristics



Typical Transfer Characteristics

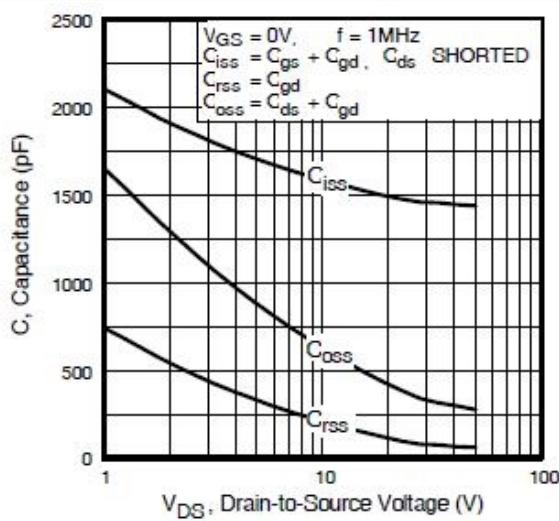


Normalized On-Resistance Vs.
Temperature

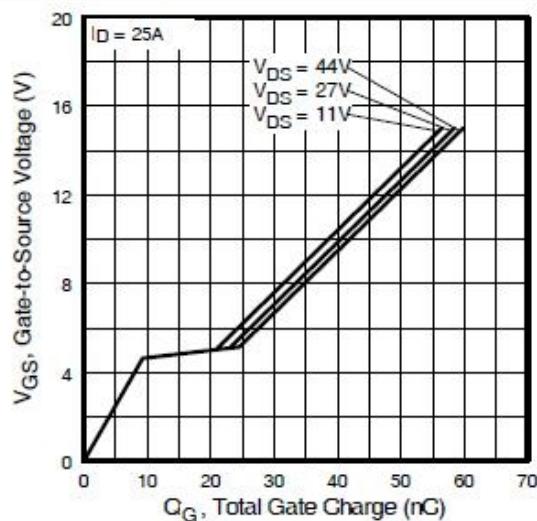


ZL MOSFET

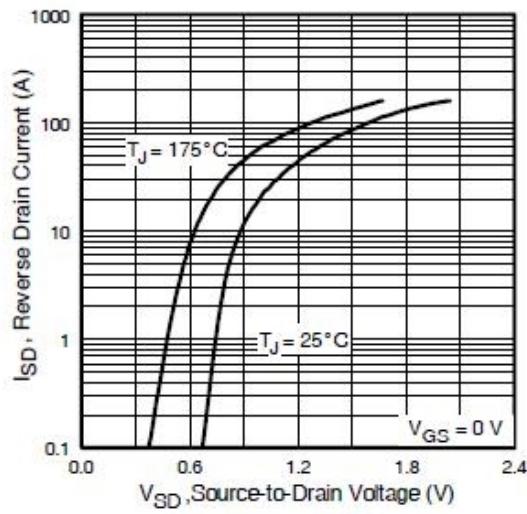
ZLZ44T



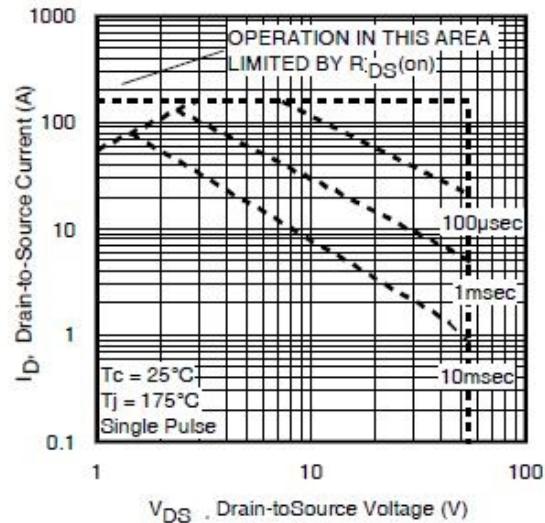
Typical Capacitance Vs. Drain-to-Source Voltage



Typical Gate Charge Vs. Gate-to-Source Voltage



Typical Source-Drain Diode Forward Voltage

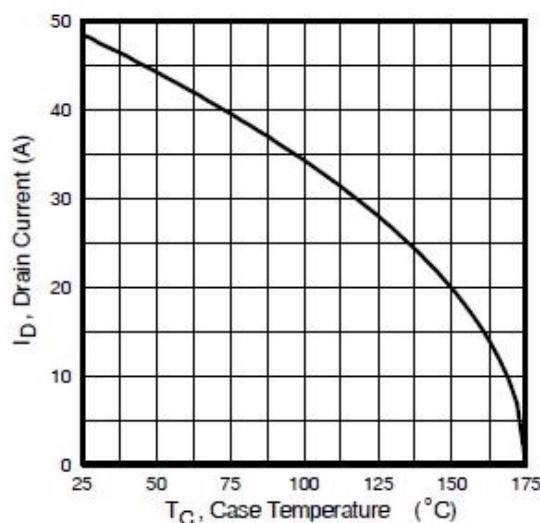


Maximum Safe Operating Area

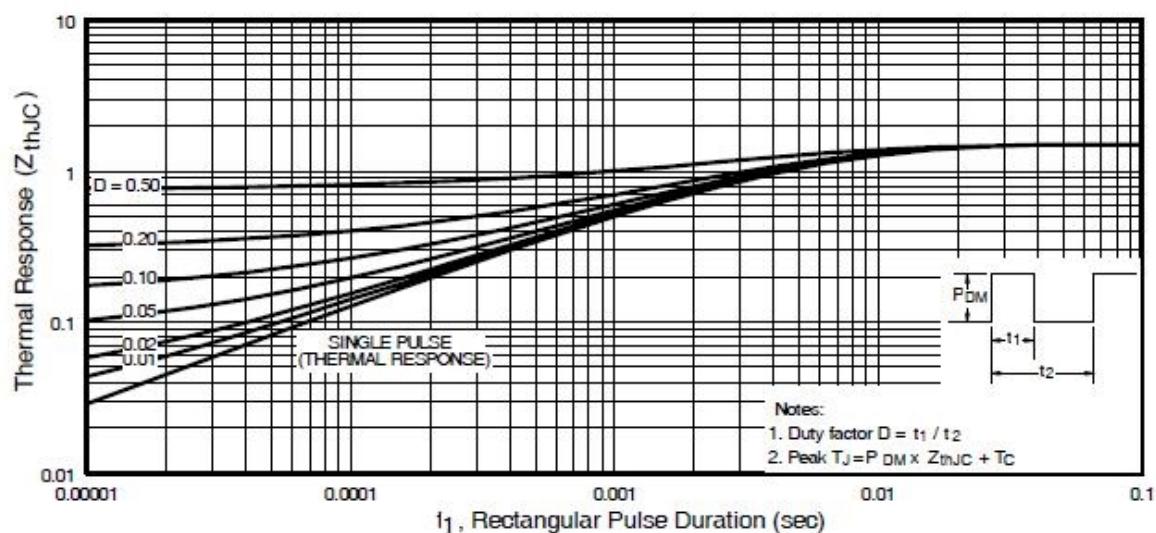


ZL MOSFET

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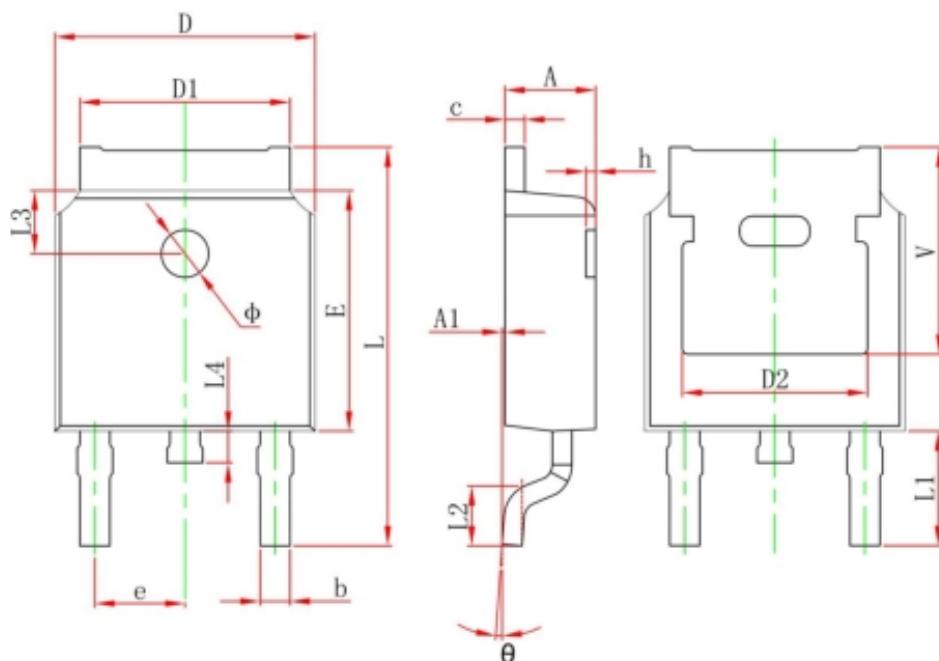


Maximum Drain Current Vs. Case Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Case

TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	